

Circuit Module having Interleaved Groups of Circuit Chips

ABSTRACT

5 A circuit module has a carrier (10) and multiple stacks of
circuit chips arranged on a surface of the carrier. Each
stack has multiple circuit chips arranged in different
layers. The circuit chips are grouped in different groups,
wherein the groups are not active at the same time. The
10 circuit chips are arranged such that circuit chips belonging
to the same group are arranged in different layers in
adjacent stacks.

Fig. 1